

# MECHANICAL CASE OUTLINE

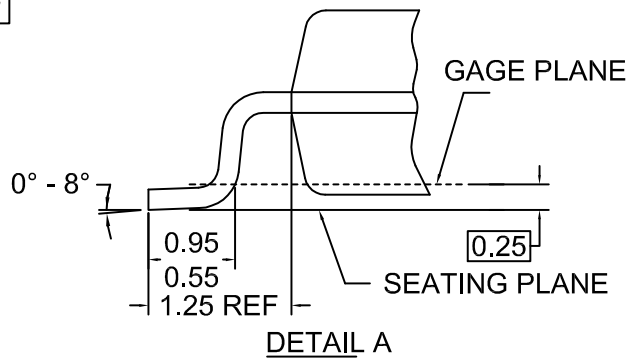
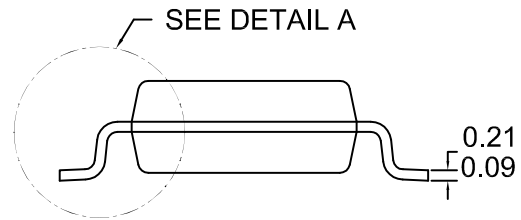
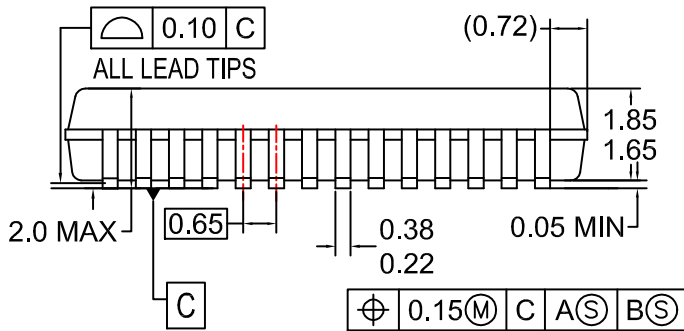
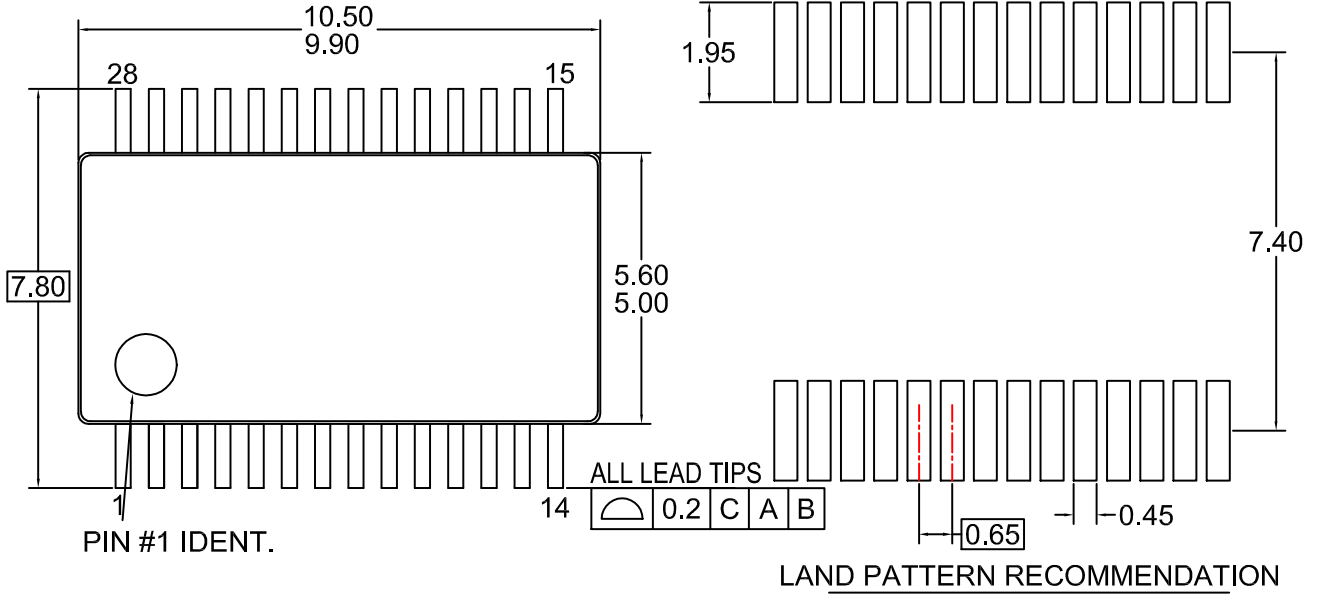
## PACKAGE DIMENSIONS

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**NOTES:**

- A. CONFORMS TO JEDEC REGISTRATION MO-150, VARIATION AH.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M - 1994.

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